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MiTAC Computing

ORAN & OCP Platforms

IA Low Latency, High Bandwidth and Capacity solution for network infrastructure

OPEN PLATINUM
OPEN Compute Project
SOLUTION PROVIDER
O-RAN ALLIANCE

Product Catalog 2024 Q2 Rev.1

AOWANDA Series

OPEN INSPIRED™

5G RAN/ MEC
Multi-Node Edge Computing Server

- Front I/O for Network Rack Cabinet Compatibility
- OCP Open Edge Compliable
- Enhance Power Efficiency through Centralized
- Power Supply Design
- RMC Design to Centralize Server Management

intel. XEON PLATINUM

AD211

AD1S01

AD1S02

	AD211
Form Factor	2RU
Dimension (D x W x H)	16.92" x 17.32" x 3.39" (430 x 440 x 86.3mm)
RMC Moudle	(2) 10G SFP+ ,(1) GbE, (1) USB for debug
Power Supply	(1+1) 80+ Platinum 2000W 110/220AC input or 80+ Platinum 2000W -48VDC input
Operating Temp.	-5° C ~ 50° C (23° F~ 122° F) * 185W CPU

	AD1S01	AD1S02
Supported Processor	(1) 3rd Gen Intel® Xeon® Scalable Processor	
Memory	(8) DDR4 DIMM slots (1DPC) , up to 2TB RDIMM(3DS) total , max. 3200MT/s	
TPM Support	TPM Header for SPI 2.0 for BIOS	
BMC	ASPEED AST2600 • Support IPMI 2.0 and DMTF Redfish® 1.8	
Cooling	(3+1) 4056 Redundant FANs	
PCIE Expansion Slots	(1) FHHL PCIe Gen4 x16 (1) OCP NIC 3.0 PCIe Gen4 x16	(1) FHHL PCIe Gen4 x16 (1) HHHL PCIe Gen4 x16
Storage	(2) E1.S PCIe Gen4 SSD bays (2) 2280/110mm M.2 (SATA/PCIe Gen3 x4)	(2) 2280/110mm M.2 (SATA/PCIe Gen3 x4)

FIRESTONE2 Series

5G MEC, UPF Edge Server

- 2S 3rd Gen Xeon SP processors
- 2U short chassis
- Front access
- Support Double Width GPU Card
- AC or -48VDC Power Input
- Accelerators for inference workloads
- NFVI - Expansion slots for network
- Option for expansion drive

intel. XEON PLATINUM

NVIDIA.

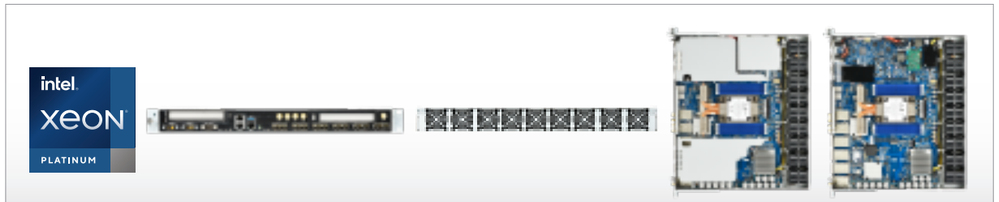
	FS2D11 Edge Server
Form Factor	2RU
Dimension (D x W x H)	17.23" x 17.17" x 3.27" (450 x438.5 x 87mm)
Supported Processor	(2) 3rd Gen Intel® Xeon® Scalable Processor
Memory	(8) DDR4 DIMM slots (1DPC) , up to 4TB RDIMM(3DS) total max. 3200MT/s
BMC	ASPEED AST2500 • Support IPMI 2.0 and DMTF Redfish®
PCIE Expansion Slots	(2) FHFL PCIe Gen4 x16 (4) FHHL PCIe Gen4 x8
Storage	(6) 2.5" SATA SSD bays (option support 2* U.2) (1) 22110/2280/2242 (X2 PCIe Gen 3)
Cooling	(3+1) 8038 Hot Swappable Redundant FANs
Power Supply	(1+1) 80+ Platinum 800W or 1200W 110/220AC input or 80+ Platinum 800W -48VDC input
Operating Temp.	-5° C ~ 50° C (23° F~ 122° F)

WHITESTONE Series

5G CU/DU Edge Server

- Single-socket 3rd Gen Intel Xeon Processor
- 1U Short Depth Chassis (380mm)
- Front Access for easy maintenance
- Dual Feed Power Input
- NICs onboard for 5G vRAN FH/MH
- Supports IEEE1588 V2 PTP & SyncE

Red Hat

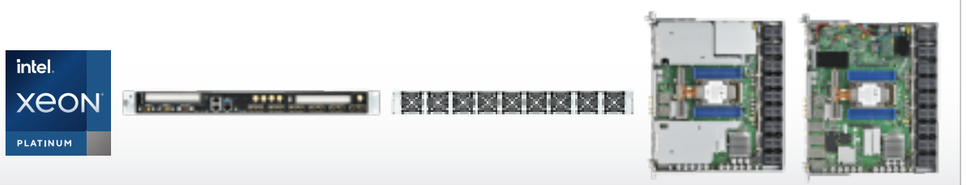


	WS1S01-S (Standard)
Form Factor	1RU
Dimension (D x W x H)	14.6" x 17.25" x 1.68" (380 x438 x43mm)
Processor	(1) 3rd Gen Intel® Xeon® Scalable Processor
Memory	(8) DDR4 DIMM slots (1DPC) , up to 2TB RDIMM(3DS) total, max. 3200MT/s
Storage	(2) 2280/110mm M.2 (SATA/PCIe Genn3 x4)
Management Port	(1) GbE for Console, (1) GbE for GNSS
Power Supply	Dual Feed / -48VDC power input
PCIE Expansion Slots	(2) FHHL PCIe Gen4 x16
FH& MH Interface	(4) 25G SFP28 + (8)10G SFP+
FEC Accelerator	Intel Mt Bryce eASIC
Synchronization	• T-BC and T-TGM capabilities (IEEE1588 v2) • Sync-E synchronization • Up to 8 hour hold-over option • Options for built-in or external GPS receiver
Operating Temp.	-5° C ~ 55° C (23° F~ 131° F) * 185W CPU

WHITESTONE 2 Series

ORAN Edge Computing

- 4th Gen Xeon SP processors
- 1U short depth front access chassis
- Extended temperature range
- Intel Mount Bryce FEC Accelerator
- GPS & IEEE1588 Sync-E Support
- 48Vdc Power Input



	WS1S11-S (Standard)
Form Factor	1RU
Dimension (D x W x H)	14.6" x 17.25" x 1.68" (380 x438 x43mm)
Processor	(1) 4th Gen Intel® Xeon® Scalable Processor, SPR-EE
Memory	(8) DDR4 DIMM slots (1DPC) , up to 2TB RDIMM(3DS) total, max. 3200MT/s
Storage	(2) 2280/110mm M.2 (SATA/PCIe Genn3 x4)
Management Port	(1) GbE for Console, (1) GbE for GNSS
Power Supply	Dual Feed / -48VDC power input
PCIE Expansion Slots	(2) FHHL PCIe Gen4 x16
FH& MH Interface	(4) 25G SFP28 + (8)10G SFP+
FEC Accelerator	in SPR-EE CPU
Synchronization	• T-BC and T-TGM capabilities (IEEE1588 v2) • Sync-E synchronization • Up to 8 hour hold-over option • Options for built-in or external GPS receiver
Operating Temp.	-5° C ~ 55° C (23° F~ 131° F) * 205W CPU

MiTAC Computing

OCP Platforms

OPEN PLATINUM

OPEN Compute Project SOLUTION PROVIDER

Continuous Commitment

MiTAC is committed to delivering OCP based cloud solutions in 2021 which bring great advantages in cost and flexibility in SDN, and NFV cloud service deployments

OCP Compute Node

OCP ESA Kit

OCP Server

OCP JBOD Storage -Lake Erie

Broadcom SAS4 expender
A Density and Flexable storage design for Open Rack V3

- Hot swappable HDD and storage sled
- Tool-Less Design for Easy Maintenance
- Density HDD bays

BROADCOM

	LE2350L
Form Factor	2OU 3 Sleds
Dimension (D x W x H)	35.46" x 21.14" x 3.75" (900 x 537 x 95.2mm)
Supported Processor	(3) Broadcom SAS4 X24 expander, One each sled
Storage HDD	(36) 3.5" SATA3/SAS3 HDD, twelve each sled
I/O Port	(3) SAS4 external SFF-8674 (Mini SAS HD) (1) USB type C for debug , (1) Health LED (2) ACT LED (2) Link LED , each sled
Management	• LED Control • Temp Monitoring • Drive/Array Control • Fan Control/Monitor • Alarms/Notifications
Power Supply	Centralized OCP power shelf (48VDC Bus Bar input)
Operating Temp.	10° C ~ 35° C (50° F~ 95° F)

OCP Server - Goldstone
GS1D11 Series

4th Gen Intel® Xeon® Scalable Processor Power Effiency design for new Open Rack V3 architecture

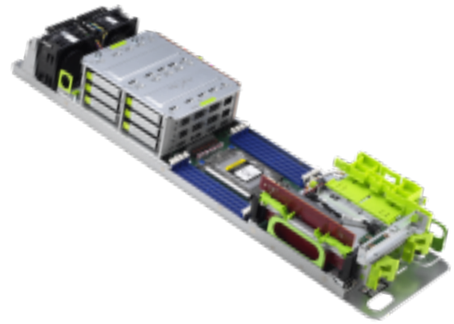
- Various SKUs for Different Usage Scenarios
- Compatible with both Open Rack v3
- Supporting OCP DC-SCM for management and security

	GS1D01
Form Factor	1OU Sled
Dimension (D x W x H)	31.1" x 21.14" x 1.76" (790 x 537 x 44.8mm)
Supported Processor	(2) 4th Gen Intel® Xeon® Scalable Processor *
Memory	(16+16) DDR5 DIMM slots (2DPC) , up to 8TB RDIMM (3DS) total, max. 4800MT/s
Management Port	(1) Dedicated GbE for management
BMC	ASPEED AST2600 • Support IPMI 2.0 and DMTF Redfish
TPM Support	TPM Header for SPI 2.0 for BIOS
Power Supply	Open Rack V3 bus bar
Operating Temp.	10° C ~ 35° C (50° F~ 95° F)

	Standard (GS1D01-S)	Ultra (GS1D01-U)
PCIE Expansion Slots	(2) HHHL PCIe Gen5/4 x16 (1) OCP NIC 3.0 PCIe Gen5/4 x16	(2) HHHL PCIe Gen5/4 x16 (1) OCP NIC 3.0 PCIe Gen5/4 x16
Storage	(2) 2.5" SATA/SAS/U.2 (SATA3/ PCIe G5/4) (1) 2280/110mm M.2 (PCIe 3 x4)	(4) E1.S SSD bays (PCIe G5/4) (1) 2280/110mm M.2 (PCIe Gen3 x4)

* up to 350W @25C
up to 270W @27C
up to 225W @35C

OCP Server - Capri
E8020 Series



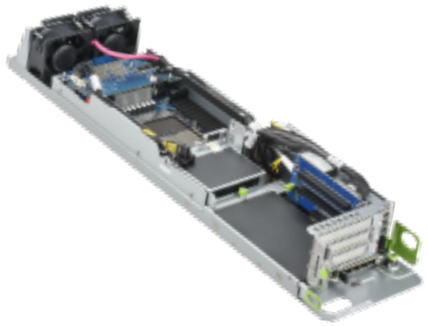
AMD EPYC™ 7002/7003 Processor Series Density Optimized for Software Defined Data Center

- High Density Storage, up to 10 U.2 SSDs with Ultra SKU
- Various SKUs for Different Usage Scenarios
- Compatible with Open Rack v2
- Compatible with 19" EIA Rack through MiTAC ESA Kit
- Tool-Less Design for Easy Maintenance

	E8020
Form Factor	2OU Sled
Dimension (D x W x H)	28.46" x 6.87" x 3.5" (724 x 175 x 89mm)
Supported Processor	(1) AMD EPYC™ 7002 (Rome) / 7003 (Milan) Series Processor
Memory	(8) DDR4 DIMM slots (1DPC) , up to 2TB RDIMM (3DS) total, max. 3200MT/s
Management Port	(1) GbE RJ45 with NCSI
BMC	ASPEED AST2500 • Support IPMI 2.0 and DMTF Redfish® 1.7
TPM Support	TPM Header for SPI 2.0 for BIOS
Power Supply	Centralized OCP power shelf (12V DC)
Operating Temp.	10° C ~ 35° C (50° F~ 95° F)

	Advanced (E8020-A)	Ultra (E8020-U)
PCIE Expansion Slots	(2) HHHL PCIe Gen4 x16 (1) OCP NIC 2.0 PCIe Gen3 x16	(1) FHHL PCIe Gen4 x16 (1) OCP NIC 2.0 PCIe Gen3 x16
Storage	(6) 2.5" 7mm SATA SSD bays (6) Internal 2.5" U.2 PCIe Gen4 SSD bays (1) 2280/110mm M.2 (SATA/PCIe Gen3 x4)	(4) 2.5" U.2 SSD bays (6) Internal 2.5" U.2 PCIe Gen4 SSD bays (1) 2280/110mm M.2 (SATA/PCIe Gen3 x4)

OCP Server - Capri2
CP2S11 Series



AMD EPYC™ 9004 Processor Power Effiency design for new Open Rack V3 architecture

- High Power Efficiency
- Tool-Less Design for Easy Maintenance
- Compatible with both Open Rack v2/ v3
- Supporting High Efficiency GPU cards

Standard (CP2S11-S[48])

Ultra (CP2S11-U[48])

	CP2S11
Form Factor	2OU Sled
Dimension (D x W x H)	28.46" x 6.87" x 3.5" (724 x 175 x 89mm)
Supported Processor	(1) AMD EPYC™ 9004 (Genova) Series Processor *[1]
Memory	(8) DDR5 DIMM slots (1DPC) , up to 2TB RDIMM (3DS) total, max. 4800MT/s
Management Port	(1) Dedicated GbE for management
BMC	ASPEED AST2600 • Support IPMI 2.0 and DMTF Redfish
TPM Support	TPM Header for SPI 2.0 for BIOS
Power Supply	Centralized OCP power shelf (12VDC Bus Bar or 48VDC Bus Bar input
Operating Temp.	10° C ~ 35° C (50° F~ 95° F)

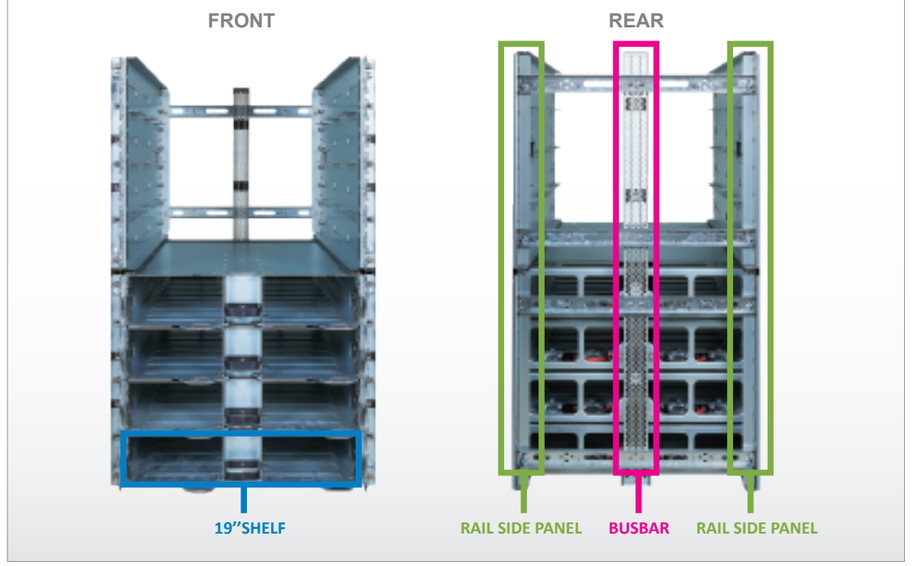
	Standard (CP2S11-S[48])	Ultra (CP2S11-U[48])
PCIE Expansion Slots	(2) HHHL PCIe Gen5/4 x16 (1) OCP NIC 3.0 PCIe Gen5/4 x16	(2) FH3/4L PCIe Gen5/4 x16 *[2] (1) FHHL PCIe Gen5/4 x8 (1) OCP NIC 3.0 PCIe Gen5/4 x16
Storage	(2) U.2 SSD bays (PCIe G5/4) (2) 2280/110mm M.2 (PCIe Gen5/4 x4)	(4) E1.S SSD bays (PCIe G5/4) (2) 2280/110mm M.2 (PCIe Gen5/4 x4)

* [1] 48VDC input: up to 360W w/o GPU card @temp.27C , up to 280W w/ GPU card (both single or DW GPU card)@ temp.35C.
12VDC input: up to 280W w/o GPU card , up to 210W w/ 1* under 70W GPU card
[2] DW GPU card: be supported with CP2S11-U48 only. Above 150W GPU card, 48VDC input SKU only
[48] supporting ORV3 canbint

● OCP Platforms | MiTAC

5G & Edge Server Platforms
OCP Platforms

OCP ESA Kit[1]



	8 OU ESA Kit	16 OU ESA Kit (Optional)
19'' Shelf (D x W x H)	30'' x 17'' x 3.9'' (765 x 431 x 98mm)	30'' x 17'' x 3.9'' (765 x 431 x 98mm)
ESA Rail Kit (D x W x H)	33'' x 19" x 15.6'' (837 x 483 x397mm)	33'' x 19" x 31.2'' (837 x 483 x 794mm)
Max. Capacity	8 sleds per ESA kit (with 4 shelves)	16 sleds per ESA kit (with 8 shelves)
Weight	40kg	78kg

[1] Following images are based on 16OU ESA Kit with 4 shelves

Open Compute in 19" EIA Rack

- To Upgrade your Rack to OCP Infrastructure
- Cost Efficiency for Edge and Cloud Computing